External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Doped silicon	Silicon (Si)	7440-21-3	0.45794	100.0	6.6
			Subtotal	0.45794	100	6.6
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.01035	100.0	0.1491
	Pure metal	Aluminium (Al)	7429-90-5	0.15611	100.0	2.25
			Subtotal	0.16646	200	2.3991
Post-plating	Pure Metal	Tin (Sn)	7440-31-5	1.73461	100.0	25
			Subtotal	1.73461	100	25
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.02331	0.04	0.336
	Copper alloy	Iron (Fe)	7439-89-6	0.05828	0.1	0.84
	Copper alloy	Copper (Cu)	7440-50-8	58.20118	99.86	838.824
			Subtotal	58.28277	100	840
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	3.39549	8.7	48.9375
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	6.24458	16.0	90
	Filler	Silica fused	60676-86-0	29.27148	75.0	421.875
	Carbon Black	Carbon black	1333-86-4	0.11709	0.3	1.6875
			Subtotal	39.02864	100	562.5
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.01648	5.0	0.2375
	Lead alloy	Silver (Ag)	7440-22-4	0.00824	2.5	0.11875
	Lead alloy	Lead (Pb)	7439-92-1	0.30486	92.5	4.39375
			Subtotal	0.32958	100	4.75
			Total	100	100	1441.2491

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